



N-Ch MOSFET

General Description

The WSR25N20G is the highest performance trench N-Ch MOSFET with extreme high cell density,which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSR25N20G meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline

Absolute Maximum Ratings

• Green Device Available

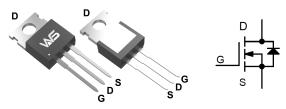
Product Summery

BV _{DSS}	R _{DSON}	I _D
200V	57mΩ	36A

Applications

- High Frequency Point-of-Load Synchronous
 Buck Converter
- Networking DC-DC Power System
- Load Switch

TO-220F Pin Configuration



Symbol **Parameter** Rating Units 200 v **Drain-Source Voltage** V_{DS} V Gate-Source Voltage ± 20 V_{GS} Continuous Drain Current, V_{GS} @ 10V¹ 36 А I_D@T_C=25℃ Continuous Drain Current, V_{GS} @ 10V¹ 25 I_D@T_C=100℃ А Pulsed Drain Current² 150 А I_{DM} Single Pulse Avalanche Energy³ EAS 273 mJ PD 90 W Total Power Dissipation³ °C T_{STG} Storage Temperature Range -55 to 175 °C ΤJ **Operating Junction Temperature Range** -55 to 175

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{eJA}	Thermal Resistance Junction-ambient ¹		62	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹		0.83	°C/W



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Electrical Characteristics (T_J=25¹C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	200			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$, I_D=1mA		0.098		V/℃
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =15A		57	68	mΩ
V _{GS(th)}	Gate Threshold Voltage		3.0	3.8	5.0	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	VGS-VDS, ID-2300A		-4.57		mV/℃
	Drain Source Leekage Current	V_{DS} =160V , V_{GS} =0V , T_J =25 $^\circ C$			1	- uA
I _{DSS}	Drain-Source Leakage Current	V_{DS} =160V , V_{GS} =0V , T_J =55 $^\circ\!\!\!\mathrm{C}$			5	
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm25V$, $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =15A		32		S
Qg	Total Gate Charge (10V)			53		
Q _{gs}	Gate-Source Charge	V_{DS} =100V , V_{GS} =10V , I_{D} =15A		11		nC
Q _{gd}	Gate-Drain Charge			15]
T _{d(on)}	Turn-On Delay Time			30		
Tr	Rise Time	V_{DD} =30V , V_{GS} =10V ,		20		
T _{d(off)}	Turn-Off Delay Time	R _G =6Ω, I _D =15A, R∟=30Ω		21		ns
T _f	Fall Time			31		
C _{iss}	Input Capacitance			2445		
Coss	Output Capacitance	V _{DS} =30V , V _{GS} =0V , f=1MHz		129		pF
C _{rss}	Reverse Transfer Capacitance			24		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}				36	А
I _{SM}	Pulsed Source Current ^{2,6}	$V_G = V_D = 0V$, Force Current			150	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =12A , TJ=25℃			1.3	V
t _{rr}	Reverse Recovery Time			48		nS
Qrr	Reverse Recovery Charge	IF=12A , dI/dt=100A/µs , Tյ=25℃		78		nC

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- **3.** Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition: Tj=25 $^\circ\!\mathrm{C},V_{DD}$ =50V,V_G=10V,L=0.5mH,Rg=25 Ω



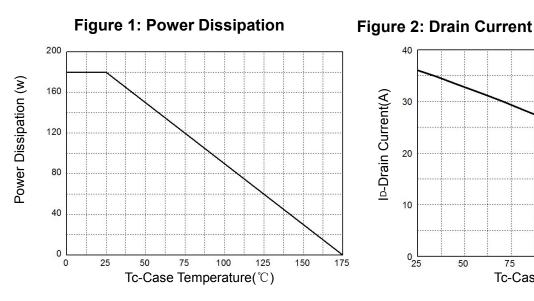
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150

175

Typical Operating Characteristics(Cont.)





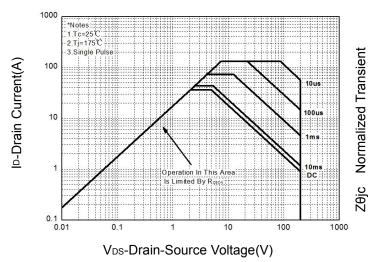


Figure 4: Thermal Transient Impedance

75

100

Tc-Case Temperature(°C)

125

40

30

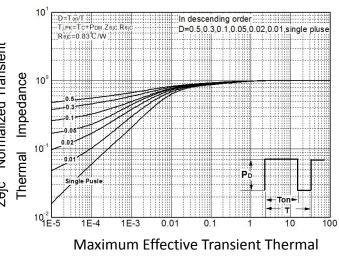
20

10

0 L

50

D-Drain Current(A)



Impedance, Junction-to-Case



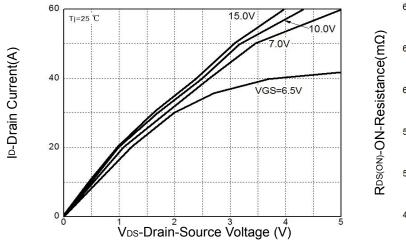
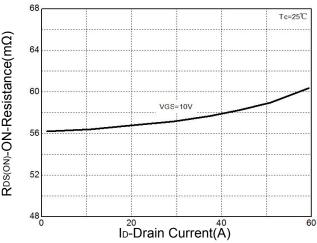


Figure 6: Drain-Source On Resistance





Typical Operating Characteristics(Cont.)

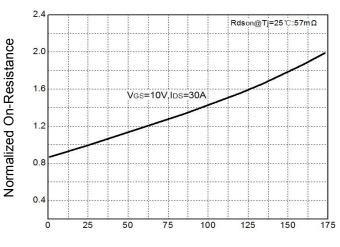
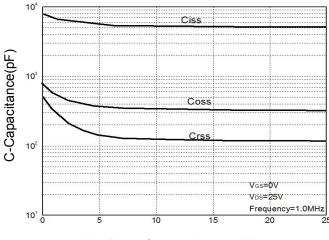


Figure 7: On-Resistance vs. Temperature

Tj-Junction Temperature (℃)

Figure 9: Capacitance Characteristics



VDS-Drain-Source Voltage (V)

Figure 8: Source-Drain Diode Forward

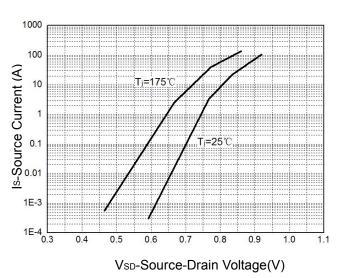
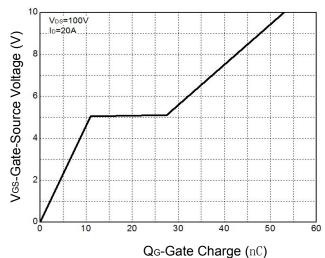


Figure 10: Gate Charge Characteristics

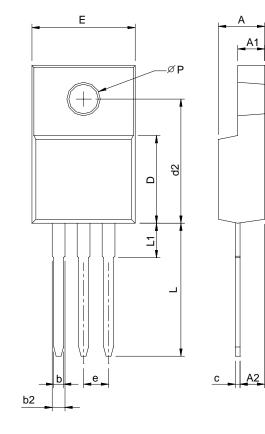


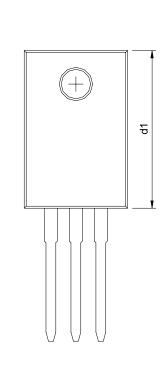


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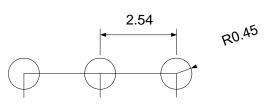
TO-220F Package Information





Ş	TO-220F				
S≻-Mano_	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
А	4.20	4.80	0.165	0.189	
A1	2.34	3.20	0.092	0.126	
A2	2.10	2.90	0.083	0.114	
b	0.50	0.90	0.020	0.035	
b2	0.91	1.90	0.035	0.075	
с	0.30	0.80	0.012	0.031	
D	8.10	9.40	0.319	0.370	
d1	14.50	16.50	0.571	0.650	
d2	12.10	12.90	0.476	0.508	
Е	9.70	10.70	0.382	0.421	
е	2.54 BSC		0.10	0 BSC	
L	13.00	14.50	0.512	0.570	
L1	1.60	4.00	0.063	0.157	
Р	3.00	3.60	0.118	0.142	

RECOMMENDED LAND PATTERN



UNIT: mm



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